

## INTEGRATED CIRCUIT PACKAGE TESTING DEVICE AND METHOD

### ABSTRACT

5       An integrated circuit (IC) package testing device using a selectable number  
of leaf springs to provide a resilient and consistent normal force to the IC package  
and the method of operating the device. The leaf springs are shaped to provide the  
proper compliance and resilient force and are shaped to fit side-by-side within the  
lid of the device. The springs can be easily changed for differently sized IC  
packages.

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